

The Stackup Legend below this is static.
If you change the stackup, update the Legend.

Layer Name	Order	Order	Order
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.OTL)	1.4mil	FR-4
Bottom Layer	(.BTL)	1.4mil	FR-4
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION	
MIN. TRACK WIDTH:	<u>8</u> MIL
MIN. CLEARANCE:	<u>0.2</u> mm
MIN. VIA PAD SIZE:	<u>24</u> MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL	
PER IPC-D-275 CLASS 2 LEVEL C	
REGISTRATION TOLERANCES: METAL +/- <u>5</u> MIL, HOLES +/- <u>3</u> MIL	
MATERIAL:	
<input type="checkbox"/> FR-408	<input checked="" type="checkbox"/> FR-4 High Tg <input type="checkbox"/> OTHER _____
THICKNESS:	<input checked="" type="checkbox"/> 62 MIL (1.6mm) +/-10% <input type="checkbox"/> OTHER _____
TOLERANCE:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2
	<input type="checkbox"/> OTHER +/- _____
BOW & TWIST:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2
	<input type="checkbox"/> OTHER +/- _____
DRILLING:	
REFERENCE:	<input checked="" type="checkbox"/> AS SHOWN <input checked="" type="checkbox"/> NC_DRILL FILES
PTH MIN COPPER THICKNESS:	<input checked="" type="checkbox"/> 1MIL <input type="checkbox"/> OTHER _____
BOARD FINISH:	
SILKSCREEN:	<input checked="" type="checkbox"/> TOP <input checked="" type="checkbox"/> BOTTOM
SILKSCREEN COLOR:	<input checked="" type="checkbox"/> WHITE <input type="checkbox"/> OTHER _____
SOLDER RESIST COLOR:	<input checked="" type="checkbox"/> GREEN <input type="checkbox"/> BLUE <input type="checkbox"/> OTHER _____
SURFACE FINISH:	<input checked="" type="checkbox"/> IMMERSION GOLD (ENG) <input type="checkbox"/> ENERP
	<input type="checkbox"/> IMM. TIN/SILVER OR EQUIV <input type="checkbox"/> OTHER _____
ARRAY/PANEL:	<input type="checkbox"/> CUT AND TRIM PER MECH LAYER 1
	<input type="checkbox"/> N.C. ROUTE <input checked="" type="checkbox"/> V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:	
<input checked="" type="checkbox"/> ANSI IPC-A-600F CLASS ->	<input type="checkbox"/> 1 <input checked="" type="checkbox"/> 2 <input type="checkbox"/> 3
<input checked="" type="checkbox"/> UL 94V-0	<input checked="" type="checkbox"/> RoHS <input type="checkbox"/> OTHER PER ORDER
ADDITIONAL REQUIREMENTS:	
MICROSECTION:	<input type="checkbox"/> YES
BARE BOARD ELEC. TEST:	<input type="checkbox"/> NONE <input checked="" type="checkbox"/> REQUIRED <input type="checkbox"/> PER ORDER
MANUFACTURER'S UL:	<input type="checkbox"/> RAIL <input type="checkbox"/> METAL <input checked="" type="checkbox"/> SILK



PROJECT TITLE:
Transimpedance Amplifier

DESIGNED FOR:
Public Release

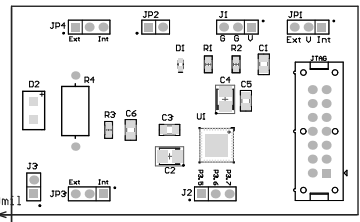
FILE NAME:
TIDM-TIA.PcbDoc

ENGINEER:
Thomas Snyder

LAYOUT BY:
Thomas Snyder

SCALE: 0.67

ALTIM DESIGNER VERSION:
10.0.0.27009



COMPONENTS MARKED 'DNP' SHOULD NOT BE ORDERED. COMPONENTS MARKED 'DNP' SHOULD NOT BE ORDERED.
ASSEMBLY VARIANT: [No Variations] ASSEMBLY VARIANT: [No Variations]

REV	DATE	BY	DESCRIPTION
1	07/18/2008	TS	Initial Release

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Layer Name	Order	Material	Thickness	Dielectric Const
Top Solder Mask	(.GTS)			Solder Resist
Top Layer	(.GTL)	FR-4	1.4mil	
Bottom Layer	(.GBL)	FR-4	1.4mil	
Bottom Solder Mask	(.GBS)			Solder Resist

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 0.2 mm
 MIN. VIA PAD SIZE: 24 MIL
 MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH MIN COPPER THICKNESS: 1MIL OTHER _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR:
 GREEN BLUE OTHER _____

SURFACE FINISH: IMMERSION GOLD (ENIG) ENERP
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S UL: RAIL METAL SILK



PROJECT TITLE:
Transimpedance Amplifier

DESIGNED FOR:
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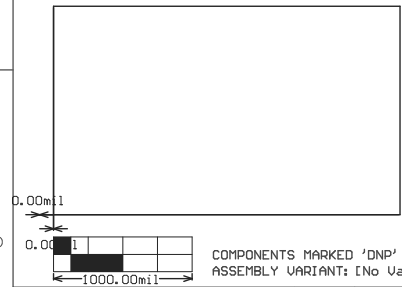
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1				Initial Release

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